

Infrared Receiver Module IRM-H5XXM3/TR2 Series

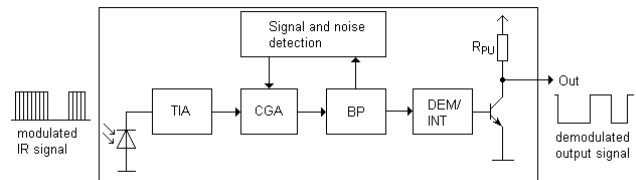


1 2 3

Pin Configuration

1. OUT
2. Vcc
3. GND

Block Diagram



Features

- High protection ability against EMI
- Circular lens for improved reception characteristics
- Available for various carrier frequencies
- min burst length: 10 cycles
- min gap length: 14 cycles
- Low operating voltage and low power consumption
- High immunity against ambient light
- High immunity against TFT and PDP backlight
- Long reception range
- High sensitivity
- Pb free and RoHS compliant

Description

The device is miniature SMD type infrared receiver that has been developed and designed by utilizing the latest IC technology.

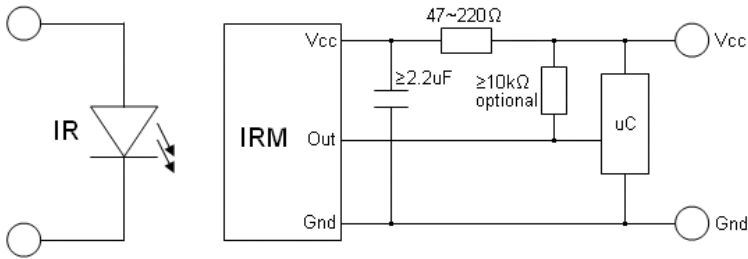
The PIN diode and preamplifier are assembled onto a lead frame and molded into an epoxy package which operates as an IR filter.

The demodulated output signal can directly be decoded by a microprocessor

Applications

- AV equipment such as TV, VCR, DVD, CD, MD, etc.
- Toy applications
- CATV set top boxes
- Multi-media Equipment
- Other devices using IR remote control

Application circuit



The RC Filter must be connected as close as possible to Vcc and GND pins.

Part number table

Model No.	Carrier Frequency
IRM-H536M3/TR2	36 kHz
IRM-H538M3/TR2	38 kHz

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Supply Voltage	V _{cc}	6	V
Operating Temperature	T _{opr}	-20 ~ +80	°C
Storage Temperature	T _{stg}	-40 ~ +85	°C
Soldering Temperature *1	T _{sol}	260	°C

*1 4mm from mold body for less than 5 seconds

Electro-Optical Characteristics (T_a=25°C, V_{cc}=3V)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit	Condition	
Current consumption	I _{cc}	---	0.4	0.6	mA	No input signal	
Supply voltage	V _{CC}	2.7	-	5.5	V		
Peak wavelength	λ _p	---	940	---	nm		
Reception range	L ₀	8	---	---	m	See chapter ,Test method'	
	L ₄₅	5	---	---			
Half angle(horizontal)	φ _h	---	±45	---	deg		
Half angle(vertical)	φ _v	---	±45	---	deg		
High level pulse width	T _H	450	---	750	μs		Test signal according to figure 1
Low level pulse width	T _L	450	---	750	μs		
High level output voltage	V _{OH}	V _{cc} -0.4	---	---	V	I _{SOURCE} ≤ 1μA	
Low level output voltage	V _{OL}	---	0.2	0.5	V	I _{SINK} ≤ 2mA	

Test method

The specified electro-optical characteristics are valid under the following conditions.

1. Measurement environment

A place without extreme light reflections.

2. External light

The environment contains an ordinary, white fluorescent lamp without high frequency modulation. The color temperature is 2856K and the illumination at the IR receiver is less than 10 Lux ($E_v \leq 10\text{Lux}$).

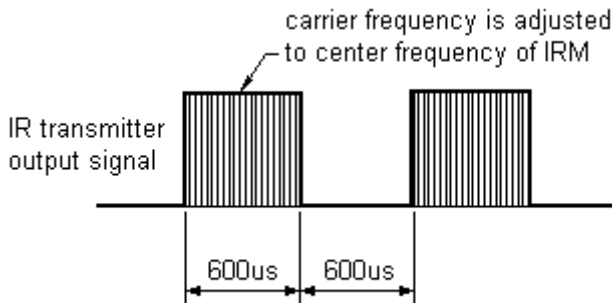
3. Standard transmitter

The test transmitter is calibrated by using the circuit shown in figure 2. The radiation intensity of the transmitter is adjusted until $V_o=400\text{mVp-p}$. Both, the test transmitter and the photo diode, have a peak wavelength of 940nm.

The photo diode for calibration is PD438B ($\lambda_p=940\text{nm}$, $V_r=5\text{V}$).

4. The measurement system is shown in Fig.-3

Fig.-1 Transmitter Wave Form



D.U.T output Pulse

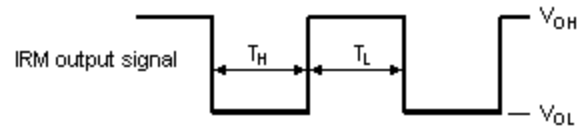


Fig.-2 standard transmitter calibration

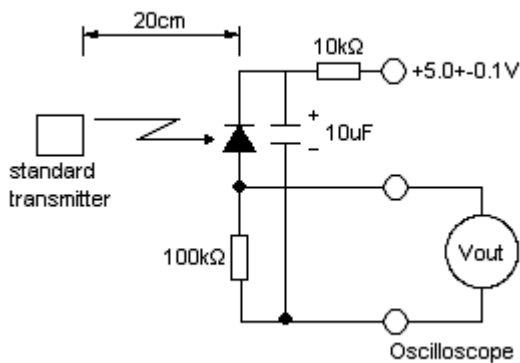
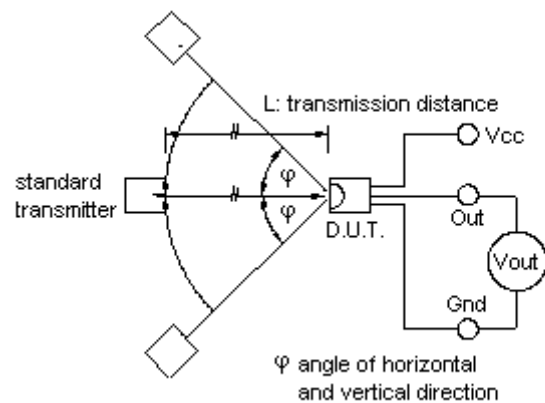


Fig.-3 Measuring System



Typical Electro-Optical Characteristics Curves

Fig.4 Relative Responsibility vs. Wavelength

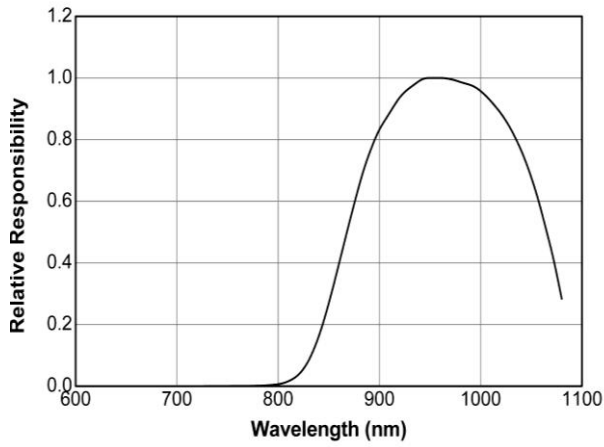


Fig.-5 Relative Sensitivity vs. Angle

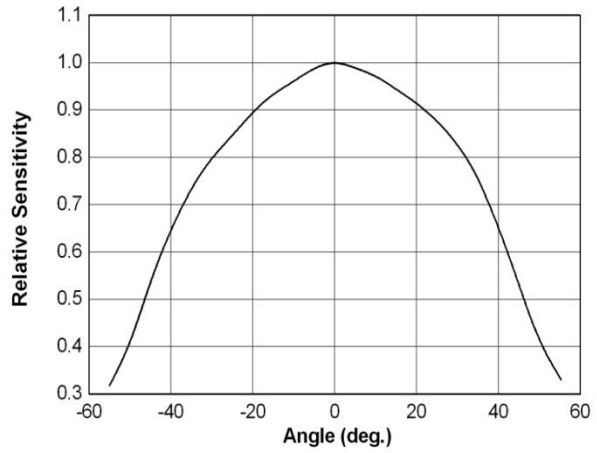


Fig.6 Variation Output Pulse Width vs. Distance

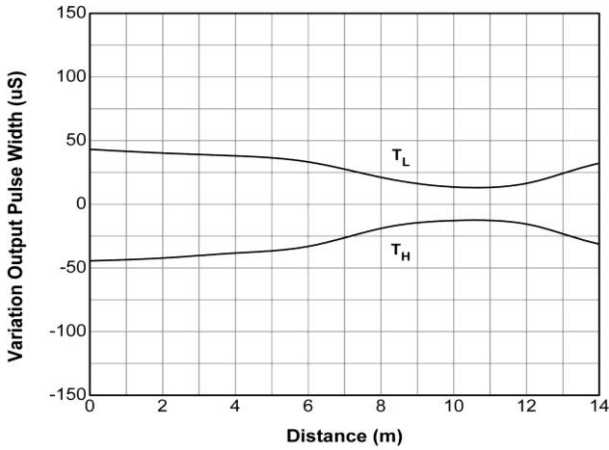


Fig.7 Relative Sensitivity vs. Supply Voltage

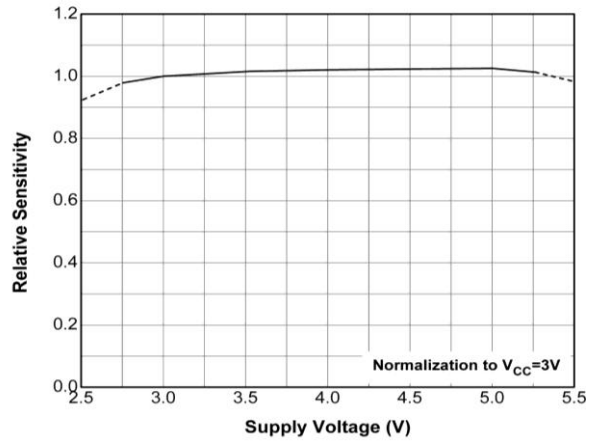
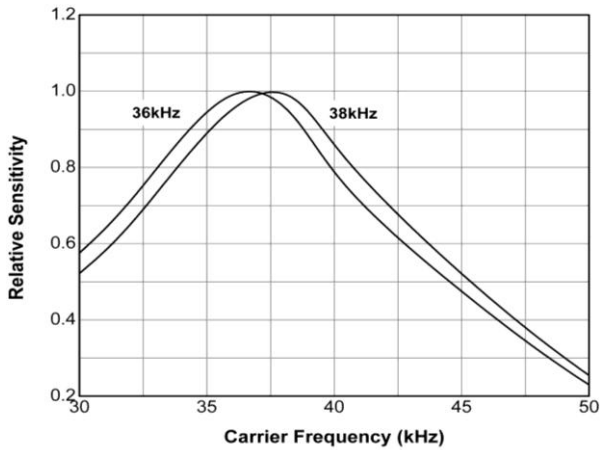
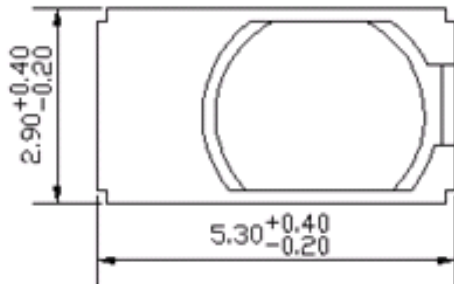


Fig.8 Relative Sensitivity vs. Carrier Frequency

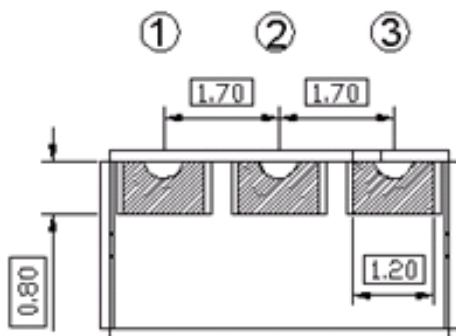
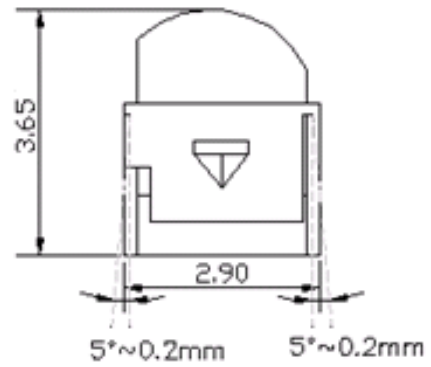
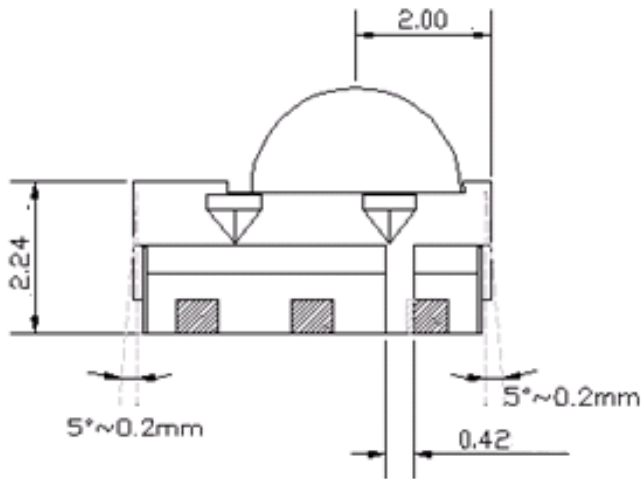


Package Dimensions
(Dimensions in mm)



Pin Function

- ①: V_{out}
- ②: V_{cc}
- ③: GND



Notes:

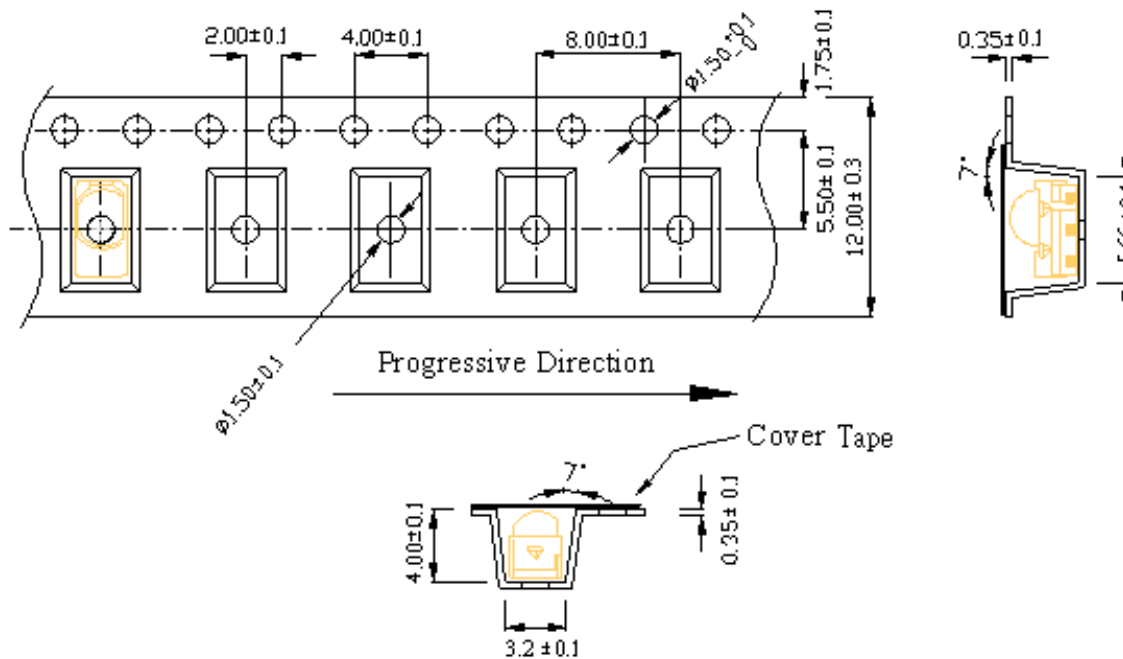
- 1. All dimensions are in millimeters.
- 2. Tolerances unless dimensions $\pm 0.3\text{mm}$.

Code compatibility

Protocol	Suitable	Protocol	Suitable
JVC	Yes	RCA	No
Matsushita	Yes	Sharp	Yes
Mitsubishi	No	Sony 12 bit ²⁾	Yes
NEC	Yes	Sony 15 bit	No
RC5	Yes	Sony 20 bit	No
RC6 ¹⁾	Yes	Toshiba	Yes
RCMM	No	Continuous Code	No

1) Best choice depends on RC6 mode. If data low time is below 22ms, M2 is the best choice, otherwise M3.
2) If only Sony 12 bit version is used, M3 is recommended otherwise M2 is the best choice.

Tape & Reel Packing Specifications (Dimensions in mm)



Packing Quantity

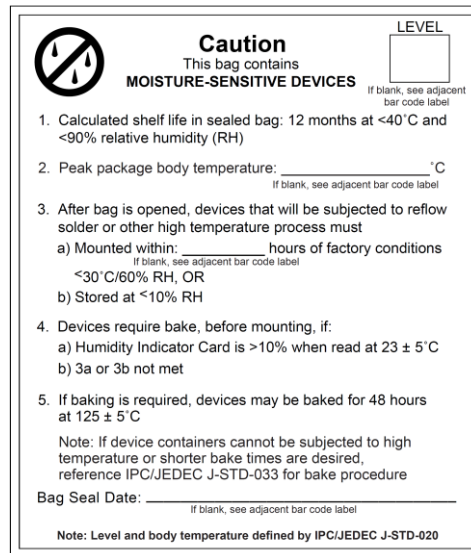
2000 pcs / Reel

5 Reels / Carton

Label format



Moisture Classification-storage and used condition label



Notes: These labels are only the examples and please be according to the actual shipping labels.

Recommended method of storage

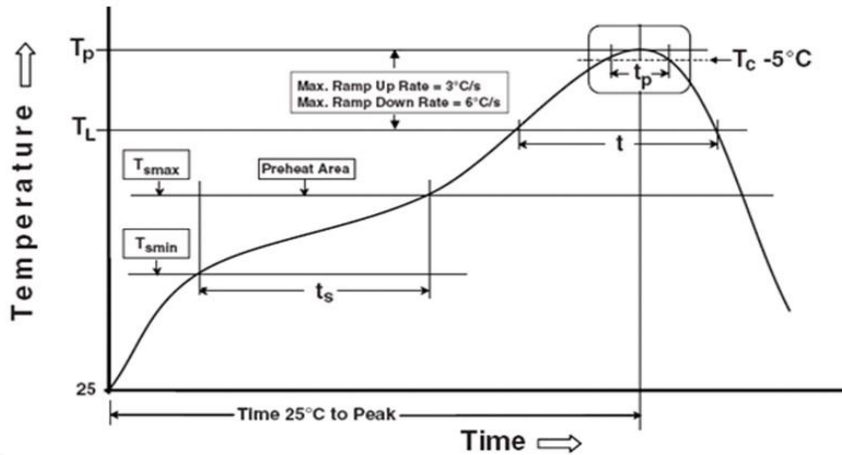
The following are general recommendations for moisture sensitive level (MSL) 4 storage and use:

1. Shelf life in sealed bag from the bag seal date: 12 months at 10°C~30°C and < 90% relative humidity (RH)
2. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must mounted within 72 hours of factory conditions at 10°C~30°C and 60%RH.
3. If the moisture absorbent material (silica gel) has faded away or the IRM has exceeded the storage time. Baking treatment is required, refer to IPC/JEDEC J-STD-033 for bake procedure or recommend the conditions: 96 hours at 60°C ± 5°C and < 5 % RH.

ESD Precaution

Proper storage and handing procedures should be followed to prevent ESD damage to the devices especially when they are removed from the Anti-static bag. Electro-Static Sensitive Devices warning labels are on the packing.

Solder Reflow Temperature Profile



Note:

Reference: IPC/JEDEC J-STD-020D

Preheat

Temperature min (T_{smin})	150 °C
Temperature max (T_{smax})	200°C
Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds
Average ramp-up rate (T_{smax} to T_p)	3 °C/second max

Other

Liquidus Temperature (T_L)	217 °C
Time above Liquidus Temperature (t_L)	60-100 sec
Peak Temperature (T_p)	260°C
Time within 5 °C of Actual Peak Temperature: $T_p - 5^\circ\text{C}$	30 s
Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature	8 minutes max.
Reflow times	2 times

Note:

1. Suggest that reflow soldering should not be done more than two times.
2. When soldering, do not put stress on the IRM device during heating.
3. After soldering, do not warp the circuit board.

Disclaimer

1. Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
2. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
3. When using this product, please observe the absolute maximum ratings and the instructions for use outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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